

**4M-BIT CMOS FAST SRAM
512K-WORD BY 8-BIT****Description**

The μ PD434008AL is a high speed, low power, 4,194,304 bits (524,288 words by 8 bits) CMOS static RAM.

Operating supply voltage is 3.3 V $\pm$ 0.3 V.

The μ PD434008AL is packaged in 36-pin plastic SOJ.

Features

- 524,288 words by 8 bits organization
- Fast access time : 12, 15, 17, 20 ns (MAX.)
- Output Enable input for easy application
- Single +3.3 V power supply

Ordering Information

Part number	Package	Access time (MAX.)	Supply current (MAX.)	
			At operating	At standby
μ PD434008ALLE-A12 ^{Note}	36-pin plastic SOJ (400 mil)	12 ns	180 mA	5 mA
μ PD434008ALLE-A15		15 ns	170 mA	
μ PD434008ALLE-A17		17 ns	160 mA	
μ PD434008ALLE-A20		20 ns	150 mA	

Note Under development

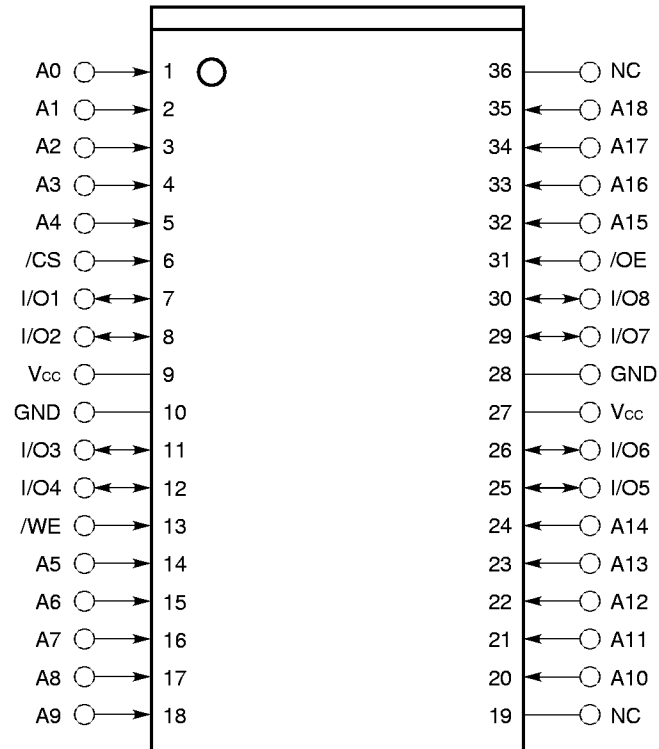
The information in this document is subject to change without notice.

Pin Configuration (Marking Side)

/xxx indicates active low signal.

36-pin plastic SOJ (400 mil)

[μPD434008ALLE]



A0 - A18 : Address Inputs
 I/O1 - I/O8 : Data Inputs / Outputs
 /CS : Chip Select
 /WE : Write Enable
 /OE : Output Enable
 Vcc : Power supply
 GND : Ground
 NC : No connection

The diagram illustrates the internal architecture of a 4,194,304-bit memory system. It features a central **Memory cell array** (4,194,304 bits) connected to an **Address buffer** and a **Row decoder**. The **Address buffer** receives inputs from **A0** and **A18**. The **Row decoder** outputs are connected to the memory cell array. The **Memory cell array** is connected to a **Sense / Switch** block, which also receives inputs from the **Address buffer** and the **Input data controller**. The **Sense / Switch** block is connected to a **Column decoder**, which in turn is connected to an **Output data controller**. The **Input data controller** is connected to the **Memory cell array** and the **Sense / Switch** block. The **Output data controller** is connected to the **Column decoder** and the **Memory cell array**. The system is controlled by **/CS**, **/OE**, and **/WE** signals, which are connected to the **Input data controller**, **Output data controller**, and the **Memory cell array** respectively. The **Input data controller** is also connected to **I/O1** and **I/O8** signals. The **Output data controller** is connected to **I/O1** and **I/O8** signals. The **Memory cell array** is connected to **I/O1** and **I/O8** signals. The **Address buffer** is connected to **I/O1** and **I/O8** signals. The **Row decoder** is connected to **I/O1** and **I/O8** signals. The **Sense / Switch** block is connected to **I/O1** and **I/O8** signals. The **Column decoder** is connected to **I/O1** and **I/O8** signals. The **Input data controller** is connected to **I/O1** and **I/O8** signals. The **Output data controller** is connected to **I/O1** and **I/O8** signals.

/CS	/OE	/WE	Mode	I/O	Supply Current
H	X	X	Not selected	High impedance	I _{SB}
L	L	H	Read	D _{OUT}	I _{CC}
L	X	L	Write	D _{IN}	
L	H	H	Output disable	High impedance	

Preliminary Data Sheet

Electrical Specifications

Absolute Maximum Ratings

Parameter	Symbol	Condition	Rating	Unit
Supply voltage	V _{CC}		−0.5 ^{Note} to +4.6	V
Input / Output voltage	V _I		−0.5 ^{Note} to +4.6	V
Operating ambient temperature	T _A		0 to +70	°C
Storage temperature	T _{stg}		−55 to +125	°C

Note −2.0 V (MIN.) (pulse width : 2 ns)

Caution Exposing the device to stress above those listed in Absolute Maximum Rating could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

Recommended Operating Conditions

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Supply voltage	V _{CC}		3.0	3.3	3.6	V
High level input voltage	V _{IH}		2.2		V _{CC} +0.3	V
Low level input voltage	V _{IL}		−0.3 ^{Note}		+0.8	V
Operating ambient temperature	T _A		0		70	°C

Note −2.0 V (MIN.) (pulse width : 2 ns)

DC Characteristics (Recommended Operating Conditions Unless Otherwise Noted)

Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input leakage current	I_{LI}	$V_{IN} = 0\text{ V to }V_{CC}$	-2		+2	μA
Output leakage current	I_{LO}	$V_{I/O} = 0\text{ V to }V_{CC}$, $/CS = V_{IH}$ or $/OE = V_{IH}$ or $/WE = V_{IL}$	-2		+2	μA
Operating supply current	I_{CC}	$/CS = V_{IL}$, $I_{I/O} = 0\text{ mA}$, Minimum cycle time	Cycle time : 12 ns		180	mA
			Cycle time : 15 ns		170	
			Cycle time : 17 ns		160	
			Cycle time : 20 ns		150	
Standby supply current	I_{SB}	$/CS = V_{IH}$, $V_{IN} = V_{IH}$ or V_{IL}			50	mA
	I_{SB1}	$V_{CC} - 0.2\text{ V} \leq /CS$, $V_{IN} \leq 0.2\text{ V}$ or $V_{CC} - 0.2\text{ V} \leq V_{IN}$			5	
High level output voltage	V_{OH}	$I_{OH} = -4.0\text{ mA}$	2.4			V
Low level output voltage	V_{OL}	$I_{OL} = +8.0\text{ mA}$			0.4	V

Remark V_{IN} : Input voltage

Capacitance ($T_A = 25\text{ }^\circ\text{C}$, $f = 1\text{ MHz}$)

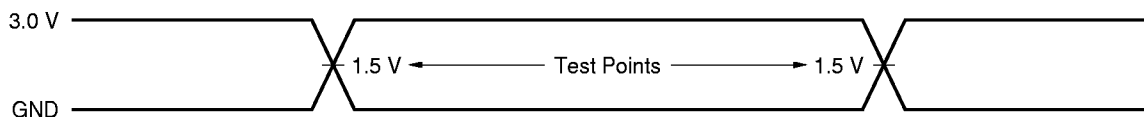
Parameter	Symbol	Test condition	MIN.	TYP.	MAX.	Unit
Input capacitance	C_{IN}	$V_{IN} = 0\text{ V}$			6	pF
Input / Output capacitance	$C_{I/O}$	$V_{I/O} = 0\text{ V}$			10	pF

- Remarks**
1. V_{IN} : Input voltage
 2. These parameters are periodically sampled and not 100% tested.

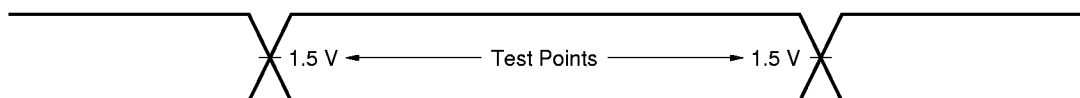
AC Characteristics (Recommended Operating Conditions Unless Otherwise Noted)

AC Test Conditions

Input Waveform (Rise and Fall Time ≤ 3 ns)



Output Waveform



Output Load

AC characteristics directed with the note should be measured with the output load shown in **Figure 1** or **Figure 2**.

Figure 1

(for tAA, tACS, tOE, tOH)

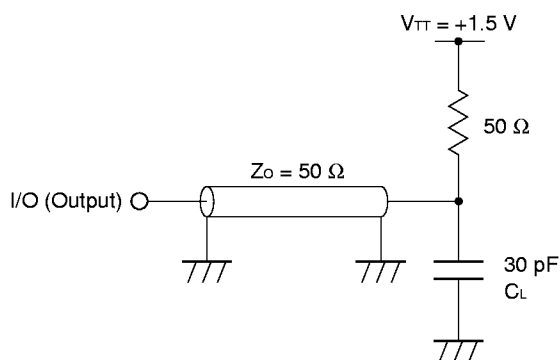
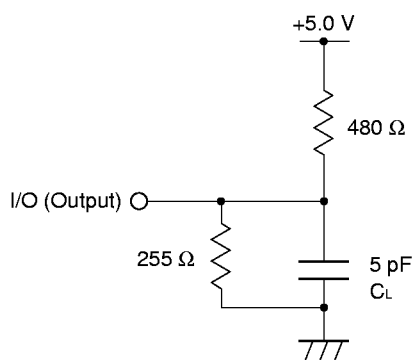


Figure 2

(for tCLZ, tOLZ, tCHZ, tOHZ, tWHZ, tOW)



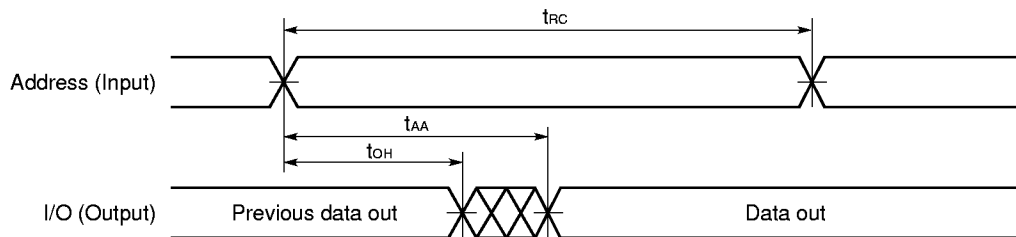
Remark C_L includes capacitances of the probe and jig, and stray capacitances.

Read Cycle

Parameter	Symbol	-A12		-A15		-A17		-A20		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read cycle time	t_{RC}	12		15		17		20		ns	
Address access time	t_{AA}		12		15		17		20	ns	1
/CS access time	t_{ACS}		12		15		17		20	ns	
/OE access time	t_{OE}		6		7		8		10	ns	
Output hold from address change	t_{OH}	3		3		3		3		ns	
/CS to output in low impedance	t_{CLZ}	3		3		3		3		ns	2, 3
/OE to output in low impedance	t_{OLZ}	0		0		0		0		ns	
/CS to output in high impedance	t_{CHZ}		6		7		8		8	ns	
/OE to output hold in high impedance	t_{OHZ}		6		7		8		8	ns	

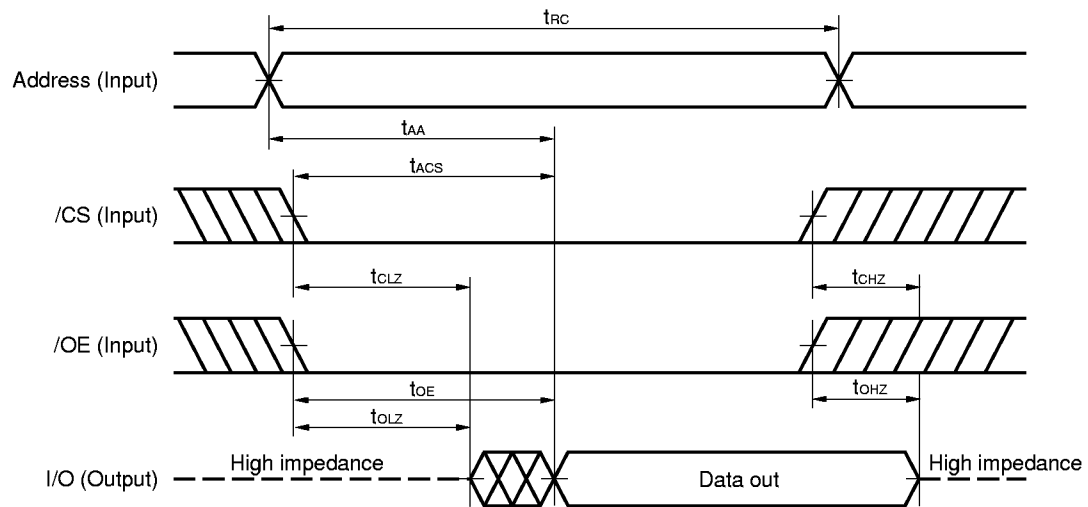
- Notes**
1. See the output load shown in **Figure 1**.
 2. Transition is measured at ± 200 mV from steady-state voltage with the output load shown in **Figure 2**.
 3. These parameters are periodically sampled and not 100% tested.

Read Cycle Timing Chart 1 (Address Access)



- Remarks**
1. In read cycle, /WE should be fixed to high level.
 2. /CS = /OE = V_{IL}

Read Cycle Timing Chart 2 (/CS Access)



Caution Address valid prior to or coincident with /CS low level input.

Remark In read cycle, /WE should be fixed to high level.

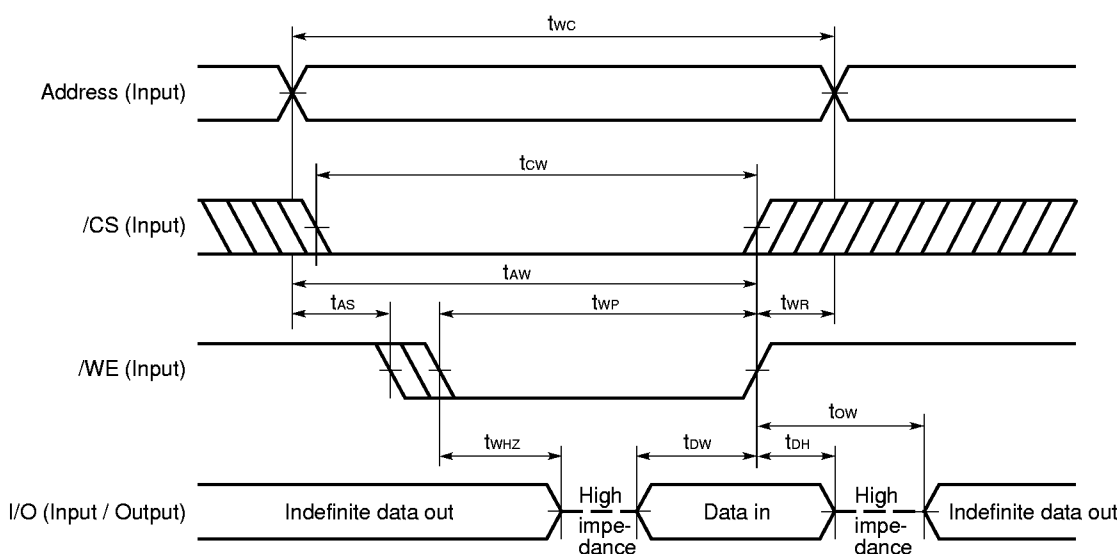
Write Cycle

Parameter	Symbol	-A12		-A15		-A17		-A20		Unit	Notes
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Write cycle time	t _{wc}	12		15		17		20		ns	
/CS to end of write	t _{cw}	8		10		11		12		ns	
Address valid to end of write	t _{aw}	8		10		11		12		ns	
Write pulse width	t _{wP}	8		10		11		12		ns	
Data valid to end of write	t _{dW}	6		7		8		9		ns	
Data hold time	t _{dH}	0		0		0		0		ns	
Address setup time	t _{AS}	0		0		0		0		ns	
Write recovery time	t _{wR}	1		1		1		1		ns	
/WE to output in high impedance	t _{WHZ}		6		7		8		8	ns	1, 2
Output active from end of write	t _{OW}	3		3		3		3		ns	

Notes 1. Transition is measured at ± 200 mV from steady-state voltage with the output load shown in Figure 2.

2. These parameters are periodically sampled and not 100% tested.

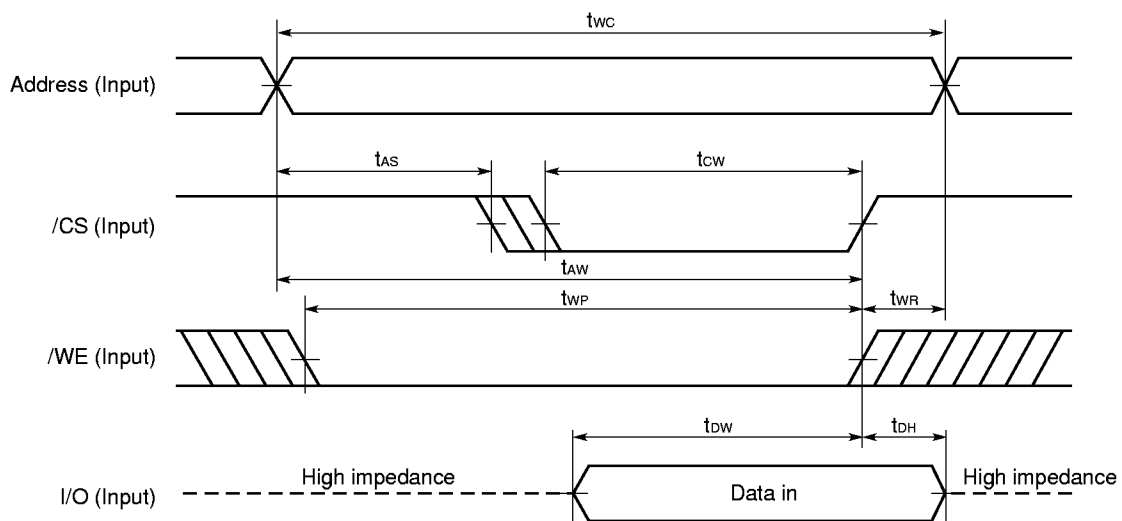
Write Cycle Timing Chart 1 (/WE Controlled)



Caution $\overline{CS}$ or $\overline{WE}$ should be fixed to high level during address transition.

- Remarks**
1. Write operation is done during the overlap time of a low level $\overline{CS}$ and a low level $\overline{WE}$.
 2. During t_{WHZ} , I/O pins are in the output state, therefore the input signals of opposite phase to the output must not be applied.
 3. When $\overline{WE}$ is at low level, the I/O pins are always high impedance. When $\overline{WE}$ is at high level, read operation is executed. Therefore $\overline{OE}$ should be at high level to make the I/O pins high impedance.

Write Cycle Timing Chart 2 (/CS Controlled)

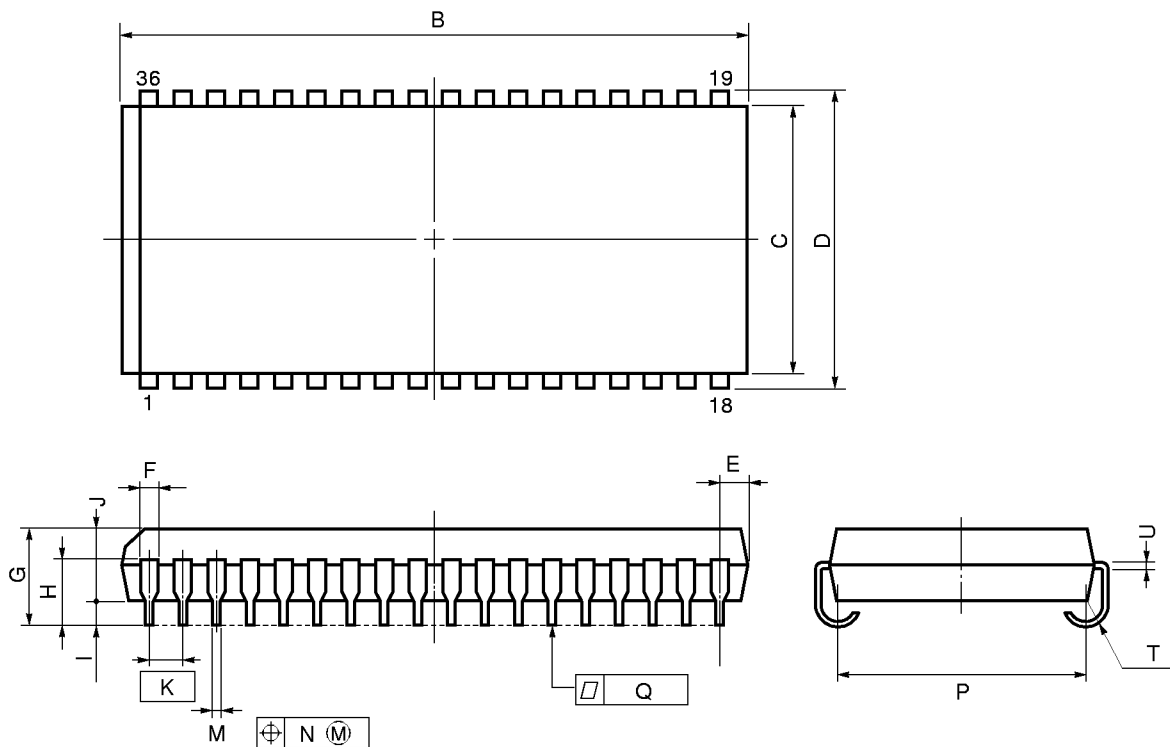


Caution /CS or /WE should be fixed to high level during address transition.

Remark Write operation is done during the overlap time of a low level /CS and a low level /WE.

Package Drawing

36 PIN PLASTIC SOJ (400 mil)



NOTE
Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

P36LE-400A

ITEM	MILLIMETERS	INCHES
B	23.6±0.2	0.929±0.008
C	10.16	0.400
D	11.18±0.2	0.440±0.008
E	1.005±0.1	0.040 ^{+0.004} _{-0.005}
F	0.74	0.029
G	3.5±0.2	0.138±0.008
H	2.545±0.2	0.100±0.008
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40±0.10	0.016 ^{+0.004} _{-0.005}
N	0.12	0.005
P	9.4±0.20	0.370±0.008
Q	0.1	0.004
T	R 0.85	R 0.033
U	0.20 ^{+0.10} _{-0.05}	0.008 ^{+0.004} _{-0.002}

Recommended Soldering Conditions

Please consult with our sales offices for soldering conditions of the μ PD434008AL.

Type of Surface Mount Device

μ PD434008ALLE : 36-pin plastic SOJ (400 mil)